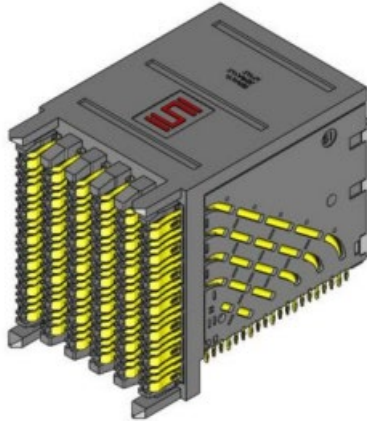




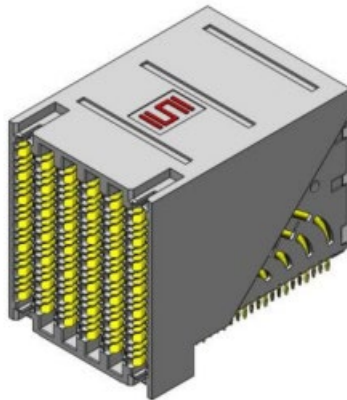
High Speed Characterization Report

EBTM-6-12-2.0-S-RA-1



Mates with

EBTF-6-12-2.0-S-RA-1



Description:

ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle (EBTM-RA to EBTF-RA), Alternate (Inverse) Mate (EBTM-RA Pin 1 Up)

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

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Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

Connector Overview

EBTM-RA/EBTF-RA series is 2.0mm column pitch high-speed backplane interconnect system. It is available in 4 or 6 differential pairs per column and press fit termination. The ExaMAX® EBTM-RA can mate with the ExaMAX® EBTF-RA in either standard coplanar mating orientation or inverse coplanar mating orientation (shown below). The data in this report is applicable to the 6-pair per column EBTM right-angle header mated to EBTF-RA receptacle, with inverse coplanar mating (EBTF-RA Pin A1 to EBTM-RA Pin A10)

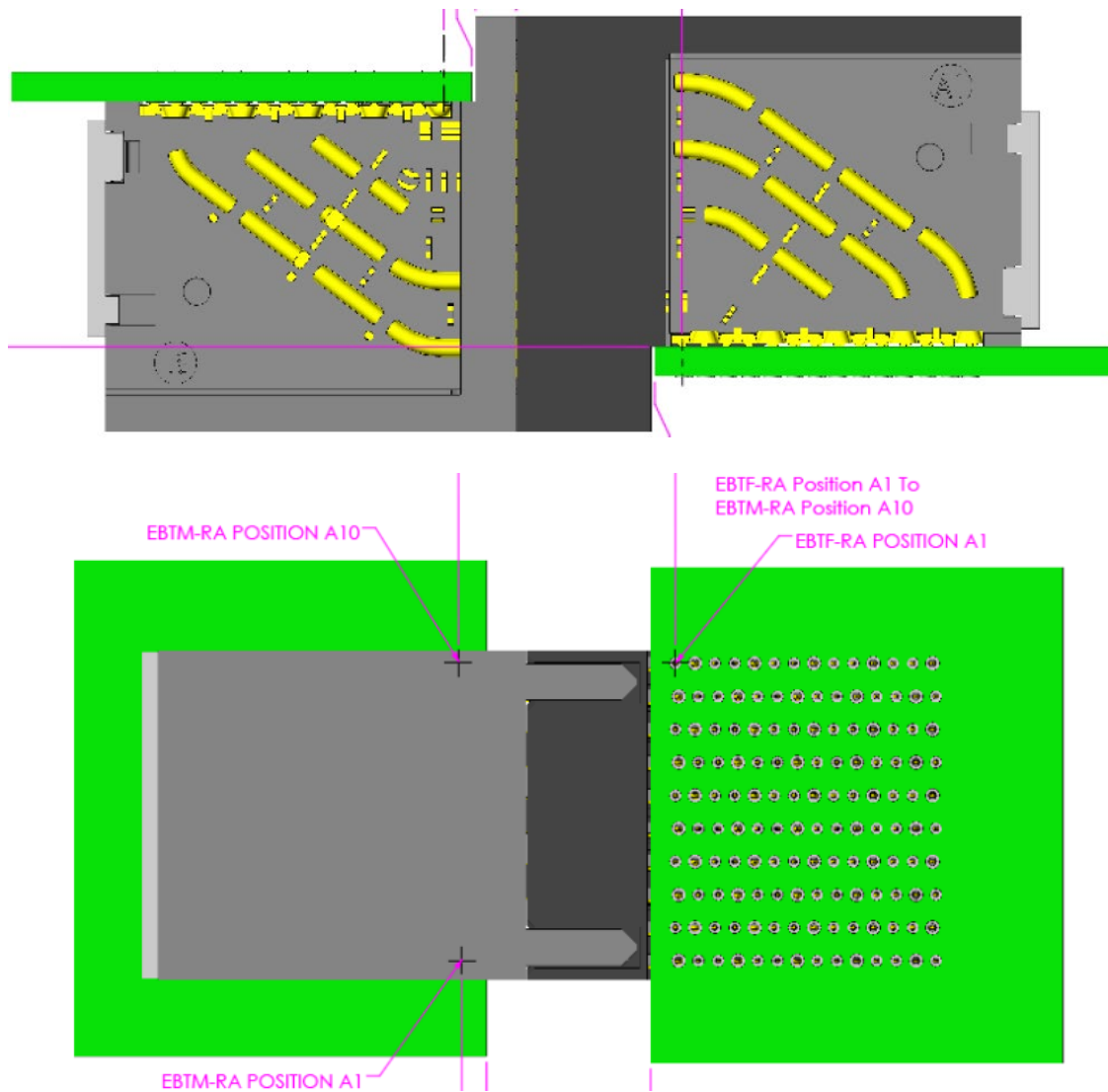


Figure 1

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

Frequency Domain Data Summary

Bandwidth Chart – Differential Insertion Loss

EBTM-RA/EBTF-RA Connector Series of inverse Co-Planar mating orientation

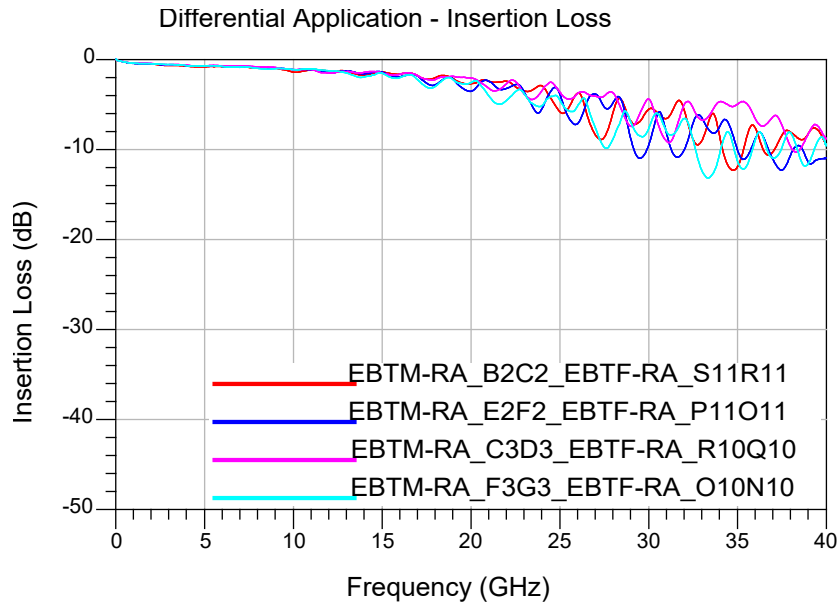


Figure 2

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

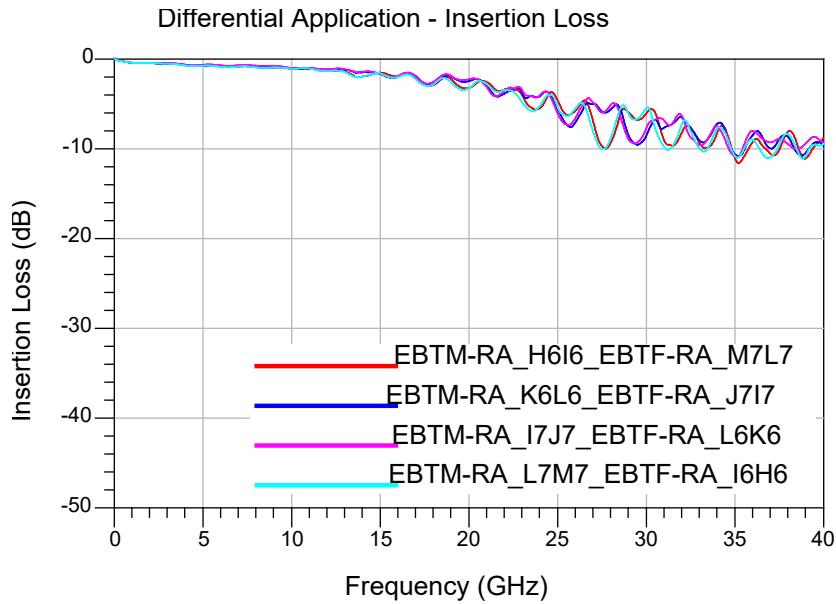


Figure 3

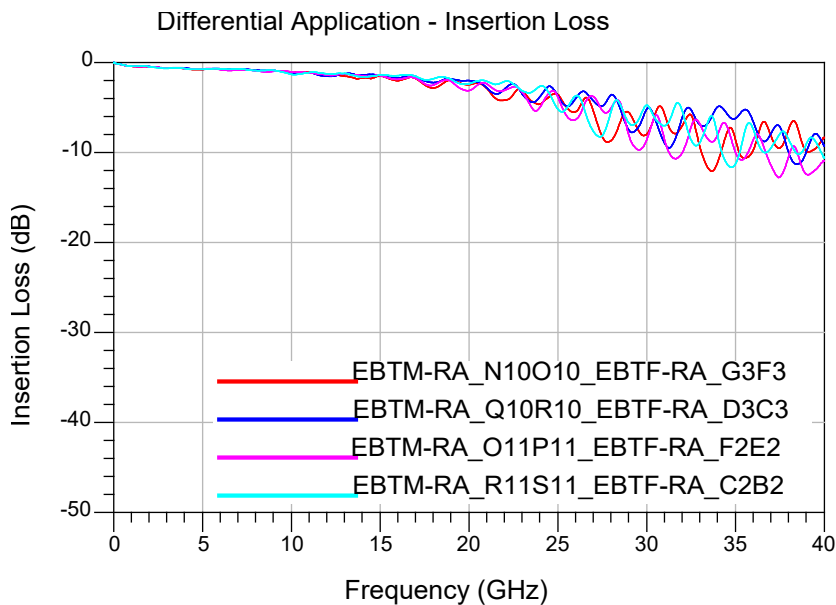


Figure 4



Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

Time Domain Data Summary

Table 1 - Differential Impedance (Ω)				
Driver	Signal Rise-time	30ps	50ps	100ps
EBTM-RA_B2C2	Maximum Impedance	102.7	102.7	102.6
	Minimum Impedance	86.3	87.7	89.2
EBTM-RA_E2F2	Maximum Impedance	102.9	102.8	102.6
	Minimum Impedance	85.7	87.8	88.7
EBTM-RA_C3D3	Maximum Impedance	104.7	104.5	103.8
	Minimum Impedance	84.6	86.1	87.7
EBTM-RA_F3G3	Maximum Impedance	103.1	103.0	102.8
	Minimum Impedance	86.9	88.2	88.9
EBTM-RA_H6I6	Maximum Impedance	102.9	102.9	102.7
	Minimum Impedance	87.0	88.1	88.7
EBTM-RA_K6L6	Maximum Impedance	102.8	102.8	102.6
	Minimum Impedance	87.1	87.6	88.4
EBTM-RA_I7J7	Maximum Impedance	105.1	104.8	104.2
	Minimum Impedance	87.0	88.1	88.8
EBTM-RA_L7M7	Maximum Impedance	103.4	103.4	103.2
	Minimum Impedance	86.6	87.3	88.4
EBTM-RA_N10O10	Maximum Impedance	102.9	102.8	102.6
	Minimum Impedance	86.0	86.6	87.6
EBTM-RA_Q10R10	Maximum Impedance	104.7	104.5	103.9
	Minimum Impedance	86.5	87.7	88.4
EBTM-RA_O11P11	Maximum Impedance	103.4	103.3	103.0
	Minimum Impedance	86.2	87.5	88.1
EBTM-RA_R11S11	Maximum Impedance	105.2	104.9	104.3
	Minimum Impedance	84.9	86.3	88.3



High Speed Characterization Report

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

Table 2 - Differential Crosstalk (%)					
Input(tr)	Driver	Receiver	30ps	50ps	100ps
NEXT	EBTM-RA_E2F2	EBTM-RA_B2C2	0.21	0.18	0.15
	EBTM-RA_E2F2	EBTM-RA_H2I2	0.15	0.14	0.11
	EBTM-RA_E2F2	EBTM-RA_C3D3	0.14	0.11	<0.1
	EBTM-RA_E2F2	EBTM-RA_F3G3	<0.1	<0.1	<0.1
	EBTM-RA_E2F2	EBTM-RA_I3J3	<0.1	<0.1	<0.1
	EBTF-RA_P11O11	EBTF-RA_S11R11	0.20	0.17	0.15
	EBTF-RA_P11O11	EBTF-RA_M11L11	0.15	0.14	0.11
	EBTF-RA_P11O11	EBTF-RA_R10Q10	0.13	0.10	<0.1
	EBTF-RA_P11O11	EBTF-RA_O10N10	<0.1	<0.1	<0.1
	EBTF-RA_P11O11	EBTF-RA_L10K10	<0.1	<0.1	<0.1
	EBTM-RA_H6I6	EBTM-RA_K6L6	0.14	0.12	0.11
	EBTM-RA_H6I6	EBTM-RA_I7J7	<0.1	<0.1	<0.1
	EBTM-RA_H6I6	EBTM-RA_L7M7	<0.1	<0.1	<0.1
	EBTF-RA_M7L7	EBTF-RA_J7I7	0.15	0.13	0.11
	EBTF-RA_M7L7	EBTF-RA_L6K6	<0.1	<0.1	<0.1
	EBTF-RA_M7L7	EBTF-RA_I6H6	<0.1	<0.1	<0.1
	EBTM-RA_O11P11	EBTM-RA_L11M11	0.15	0.13	0.12
	EBTM-RA_O11P11	EBTM-RA_R11S11	0.19	0.15	0.13
	EBTM-RA_O11P11	EBTM-RA_K10L10	<0.1	<0.1	<0.1
	EBTM-RA_O11P11	EBTM-RA_N10O10	<0.1	<0.1	<0.1
	EBTM-RA_O11P11	EBTM-RA_Q10R10	0.13	0.10	<0.1
	EBTF-RA_F2E2	EBTF-RA_I2H2	0.15	0.13	0.12
	EBTF-RA_F2E2	EBTF-RA_C2B2	0.17	0.15	0.13
	EBTF-RA_F2E2	EBTF-RA_J3I3	<0.1	<0.1	<0.1
	EBTF-RA_F2E2	EBTF-RA_G3F3	<0.1	<0.1	<0.1
	EBTF-RA_F2E2	EBTF-RA_D3C3	0.13	0.10	0.10



High Speed Characterization Report

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

FEXT	EBTM-RA_E2F2	EBTF-RA_S11R11	0.29	0.19	0.11
	EBTM-RA_E2F2	EBTF-RA_M11L11	0.22	0.13	<0.1
	EBTM-RA_E2F2	EBTF-RA_R10Q10	0.11	<0.1	<0.1
	EBTM-RA_E2F2	EBTF-RA_O10N10	<0.1	<0.1	<0.1
	EBTM-RA_E2F2	EBTF-RA_L0K10	<0.1	<0.1	<0.1
	EBTM-RA_H6I6	EBTF-RA_J7I7	0.22	0.12	<0.1
	EBTM-RA_H6I6	EBTF-RA_L6K6	<0.1	<0.1	<0.1
	EBTM-RA_H6I6	EBTF-RA_I6H6	<0.1	<0.1	<0.1
	EBTM-RA_O11P11	EBTF-RA_I2H2	0.18	0.12	<0.1
	EBTM-RA_O11P11	EBTF-RA_C2B2	0.28	0.17	<0.1
	EBTM-RA_O11P11	EBTF-RA_J3I3	<0.1	<0.1	<0.1
	EBTM-RA_O11P11	EBTF-RA_G3F3	0.17	0.11	<0.1
EBTM-RA_O11P11	EBTF-RA_D3C3	0.16	<0.1	<0.1	

Table 3- Propagation Delay (Mated Connector)

EBTM-RA_B2C2_EBTF-RA_S11R11	288 ps
EBTM-RA_E2F2_EBTF-RA_P11O11	285 ps
EBTM-RA_C3D3_EBTF-RA_R10Q10	289 ps
EBTM-RA_F3G3_EBTF-RA_O10N10	286 ps
EBTM-RA_H6I6_EBTF-RA_M7L7	285 ps
EBTM-RA_K6L6_EBTF-RA_J7I7	286 ps
EBTM-RA_I7J7_EBTF-RA_L6K6	289 ps
EBTM-RA_L7M7_EBTF-RA_I6H6	287 ps
EBTM-RA_N10O10_EBTF-RA_G3F3	285 ps
EBTM-RA_Q10R10_EBTF-RA_D3C3	288 ps
EBTM-RA_O11P11_EBTF-RA_F2E2	286 ps
EBTM-RA_R11S11_EBTF-RA_C2B2	290 ps

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

Characterization Details

This report presents data that characterizes the signal integrity response of a connector pair in a controlled printed circuit board (PCB) environment. All efforts are made to reveal typical best-case responses inherent to the system under test (SUT).

In this report, the SUT includes the connector pair and footprint effects on a typical multi-layer PCB. PCB effects (trace loss) are de-embedded from test data. Board related effects, such as pad-to-ground capacitance, are included in the data presented in this report.

Additionally, intermediate test signal connections can mask the connector's true performance. Such connection effects are minimized by using high performance test cables and adapters. Where appropriate, calibration and de-embedding routines are also used to reduce residual effects.

Differential and Single-Ended Data

Most Samtec connectors can be used successfully in both differential and single-ended applications. However, electrical performance will differ depending on the signal drive type. In this report, data is presented for differentially driven scenarios.

Connector Signal to Ground Ratio

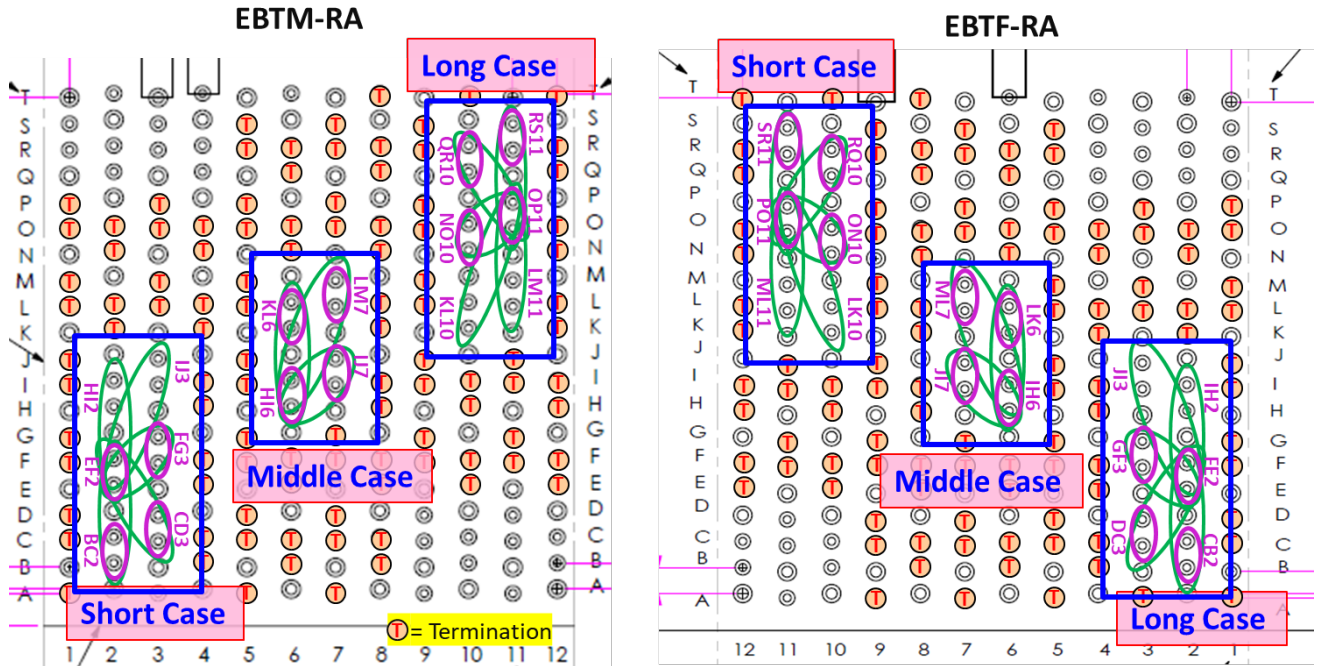
Samtec connectors are most often designed for generic applications and can be implemented using various signal and ground pin assignments. In high-speed systems, provisions must be made in the interconnect for signal return currents. Such paths are often referred to as "ground". In some connectors, a ground plane or blade, or an outer shield, is used as the signal return, while in others, connector pins are used as signal returns. Various combinations of signal pins, ground blades, and shields can also be utilized. Electrical performance can vary significantly depending upon the number and location of ground pins.

In general, the more pins dedicated to ground, the better electrical performance will be. But dedicating pins to ground reduces signal density of a connector. Therefore, care must be taken when choosing signal/ground ratios in cost or density-sensitive applications.

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

For this connector, the following array configurations were evaluated:



Pin mating configuration of Inverse Co-Planar EBTM-RA to EBTF-RA mating orientation

EBTM-RA / EBTF-RA	EBTM-RA_Column-C1, Pin # / EBTF-RA_Column-C12, Pin #	CD / RQ	FG / ON	IJ / LK	LM / IH	OP / FE	RS / CB
	Inverse Co-Planar mating orientation	EBTM-RA_C-2 / EBTF-RA_C-11, Pin #	BC / SR	EF / PO	HI / ML	KL / JI	NO / GF
EBTM-RA_C-3 / EBTF-RA_C-10, Pin #		CD / RQ	FG / ON	IJ / LK	LM / IH	OP / FE	RS / CB
EBTM-RA_C-4 / EBTF-RA_C-9, Pin #		BC / SR	EF / PO	HI / ML	KL / JI	NO / GF	QR / DC
EBTM-RA_C-5 / EBTF-RA_C-8, Pin #		CD / RQ	FG / ON	IJ / LK	LM / IH	OP / FE	RS / CB
EBTM-RA_C-6 / EBTF-RA_C-7, Pin #		BC / SR	EF / PO	HI / ML	KL / JI	NO / GF	QR / DC
EBTM-RA_C-7 / EBTF-RA_C-6, Pin #		CD / RQ	FG / ON	IJ / LK	LM / IH	OP / FE	RS / CB
EBTM-RA_C-8 / EBTF-RA_C-5, Pin #		BC / SR	EF / PO	HI / ML	KL / JI	NO / GF	QR / DC
EBTM-RA_C-9 / EBTF-RA_C-4, Pin #		CD / RQ	FG / ON	IJ / LK	LM / IH	OP / FE	RS / CB
EBTM-RA_C-10 / EBTF-RA_C-3, Pin #		BC / SR	EF / PO	HI / ML	KL / JI	NO / GF	QR / DC
EBTM-RA_C-11 / EBTF-RA_C-2, Pin #		CD / RQ	FG / ON	IJ / LK	LM / IH	OP / FE	RS / CB
EBTM-RA_C-12 / EBTF-RA_C-1, Pin #		BC / SR	EF / PO	HI / ML	KL / JI	NO / GF	QR / DC

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

Differential Impedance (denoted by purple circles):

- GSSG (Ground-positive Signal-negative Signal-Ground)

Differential Crosstalk (denoted by green circles):

- In row: from the terminals to the other terminals on the same row.
- Across row: from one row of terminals to the other row of terminals.

Other configurations can be evaluated upon request. Please contact sig@samtec.com for more information.

In a real system environment, active signals might be located at the outer edges of the signal contacts of concern, as opposed to the ground signals utilized in laboratory testing. For example, in a single-ended system, a pin-out of “SSSS”, or four adjacent single ended signals might be encountered as opposed to the “GSG” and “GSSG” configurations tested in the laboratory. Electrical characteristics in such applications could vary slightly from laboratory results. But in most applications, performance can safely be considered equivalent.

Signal Edge Speed (Rise Time):

In pulse signaling applications, the perceived performance of the interconnect can vary significantly depending on the edge rate or rise time of the exciting signal. For this report, the fastest rise time used was 30 ps. Generally, this should demonstrate worst-case performance.

In many systems, the signal edge rate will be significantly slower at the connector than at the driver launch point. To estimate interconnect performance at other edge rates, data is provided for several rise times between 30 ps and 100 ps.

For this report, measured rise times were at 20%-80% signal levels.

Frequency Domain Data

Frequency Domain parameters are helpful in evaluating the connector system’s signal loss and crosstalk characteristics across a range of sinusoidal frequencies. In this report, parameters presented in the Frequency Domain are Insertion Loss, Return Loss, and Near-End and Far-End Crosstalk. Other parameters or formats, such as VSWR or S-Parameters, may be available upon request. Please contact our Signal Integrity Group at sig@samtec.com for more information.

Frequency performance characteristics for the SUT are generated directly from network analyzer measurements.

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

Time Domain Data

Time Domain parameters indicate Impedance mismatch versus length, signal propagation time, and crosstalk in a pulsed signal environment. The measured S-Parameters from the network analyzer are post-processed using Keysight Advanced Design System to obtain the time domain response. Time Domain procedure is provided in [Appendix E](#) of this report. Parameters or formats not included in this report may be available upon request. Please contact our Signal Integrity Group at sig@samtec.com for more information.

In this report, propagation delay is defined as the signal propagation time through the connector and connector footprint. It includes 2.30 mm of PCB trace on both the EBTM-RA and EBTF-RA each. Delay is measured at 100 picoseconds signal risetime. Delay is calculated as the difference in time measured between the 50% amplitude levels of the input and output pulses.

Crosstalk or coupled noise data is provided for various signal configurations. All measurements are single disturber. Crosstalk is calculated as a ratio of the input line voltage to the coupled line voltage. The input line is sometimes described as the active or drive line. The coupled line is sometimes described as the quiet or victim line. Crosstalk ratio is tabulated in this report as a percentage. Measurements are made at both the near-end and far-end of the SUT.

Data for other configurations may be available. Please contact our Signal Integrity Group at sig@samtec.com for further information.

As a rule of thumb, 10% crosstalk levels are often used as a general first pass limit for determining acceptable interconnect performance. But modern system crosstalk tolerance can vary greatly. For advice on connector suitability for specific applications, please contact our Signal Integrity Group at sig@samtec.com.

Additional information concerning test conditions and procedures is located in the appendices of this report. Further information may be obtained by contacting our Signal Integrity Group at sig@samtec.com.

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

Appendix A – Frequency Domain Response Graphs

Differential Application – Insertion Loss

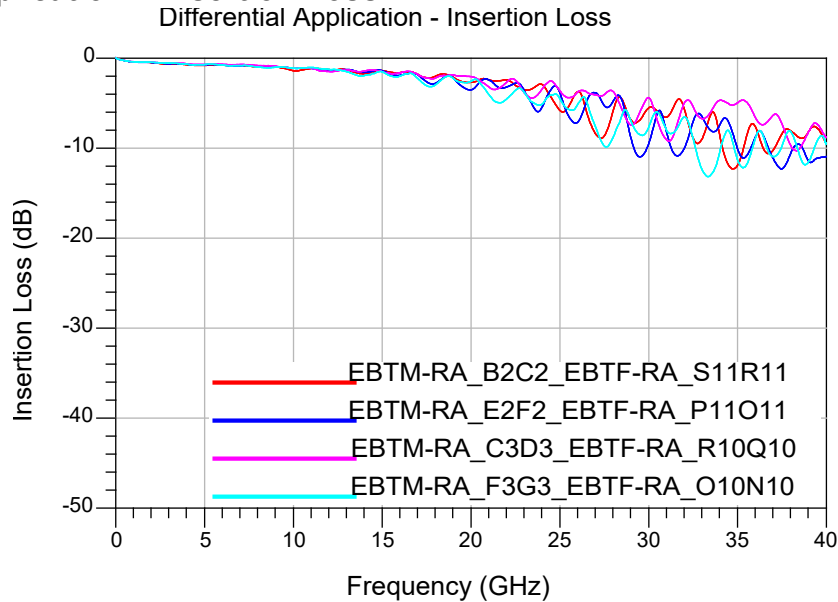


Figure 5

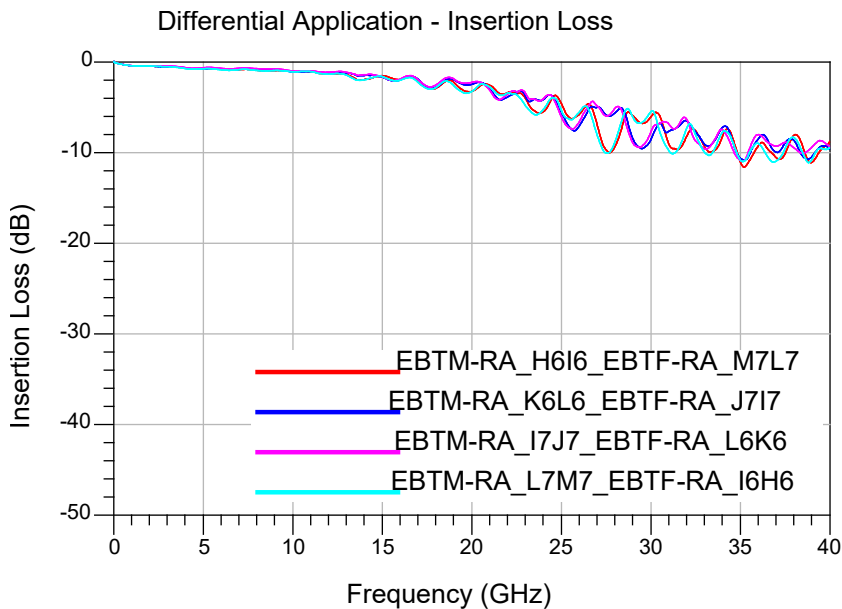


Figure 6

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

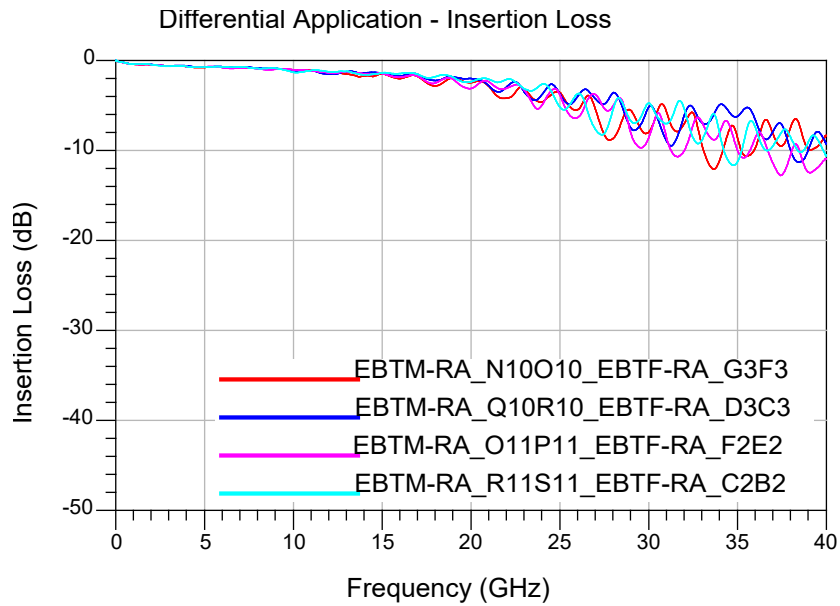


Figure 7

Differential Application – Return Loss

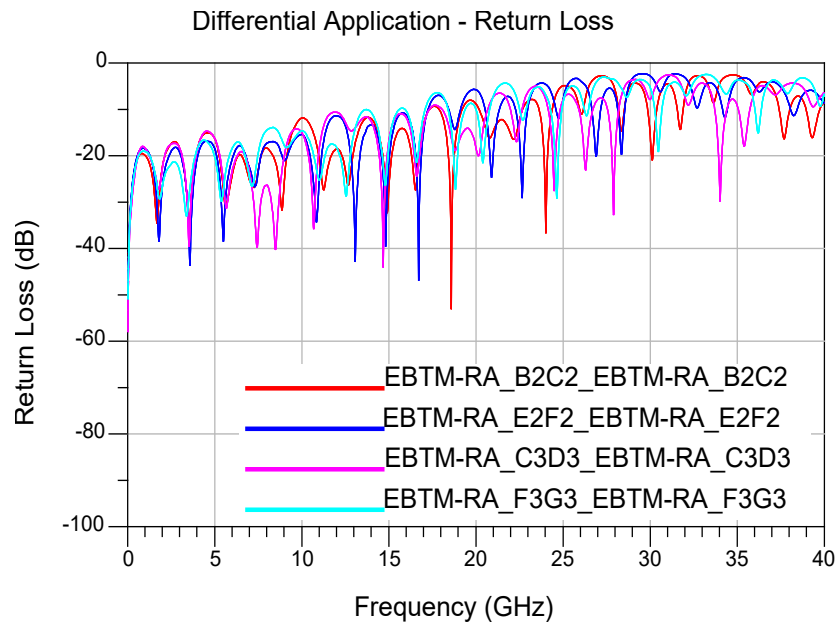


Figure 8

Series: EBTM-RA / EBTM-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

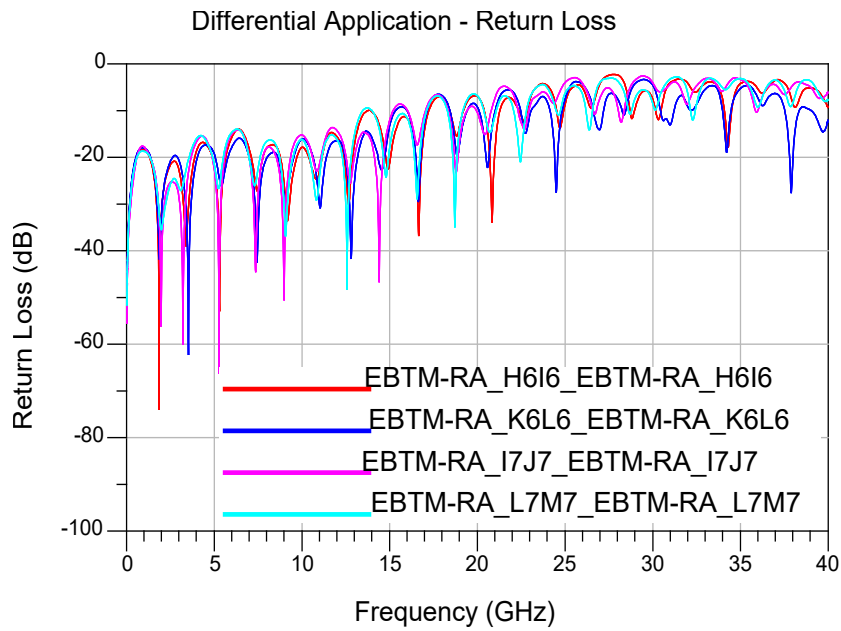


Figure 9

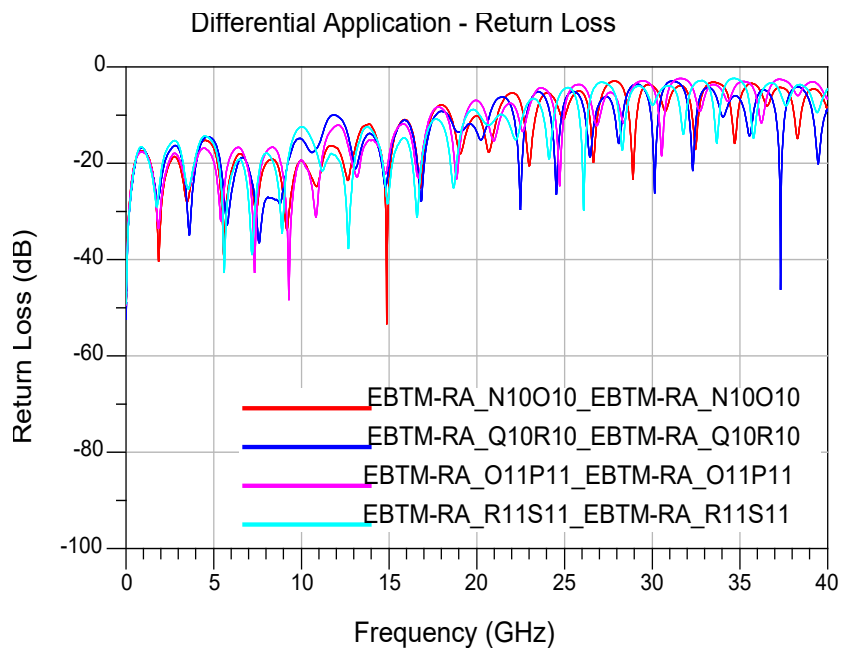


Figure 10

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

Differential Application – NEXT Configurations

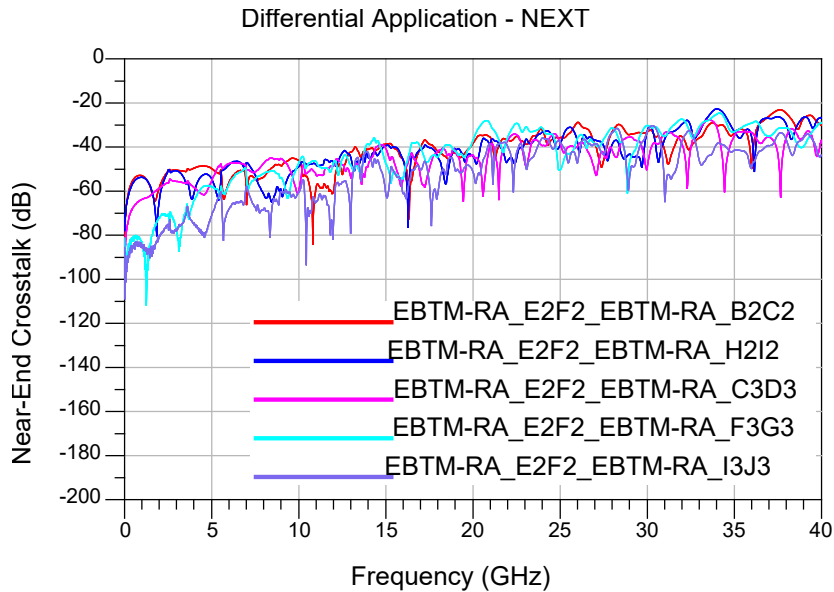


Figure 11

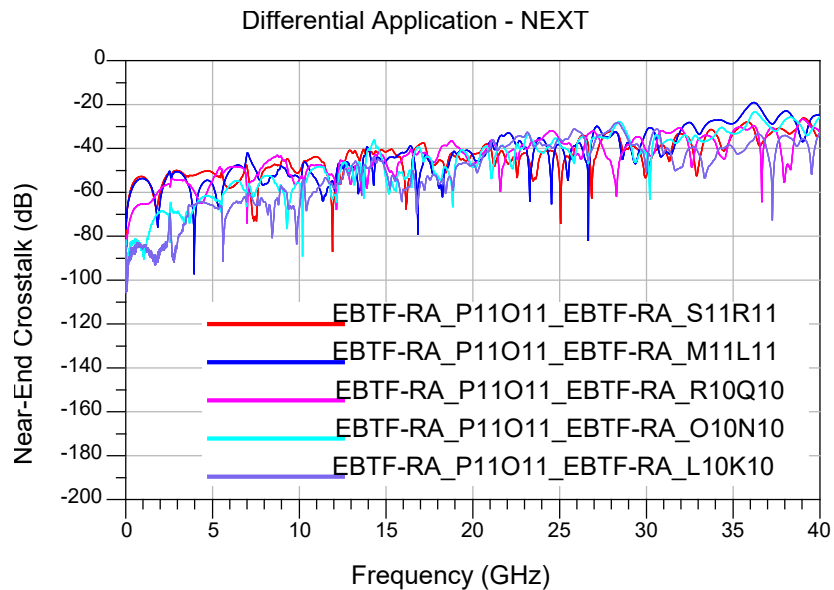


Figure 12

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

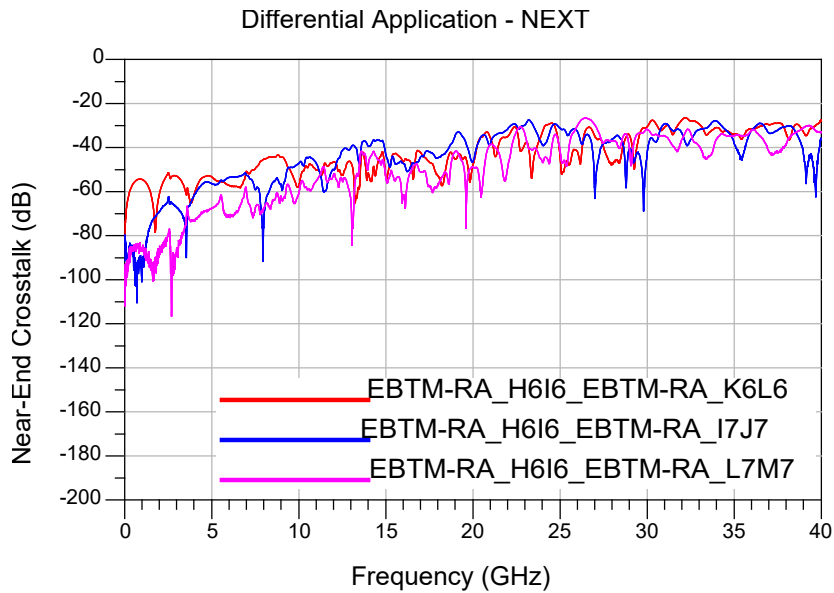


Figure 13

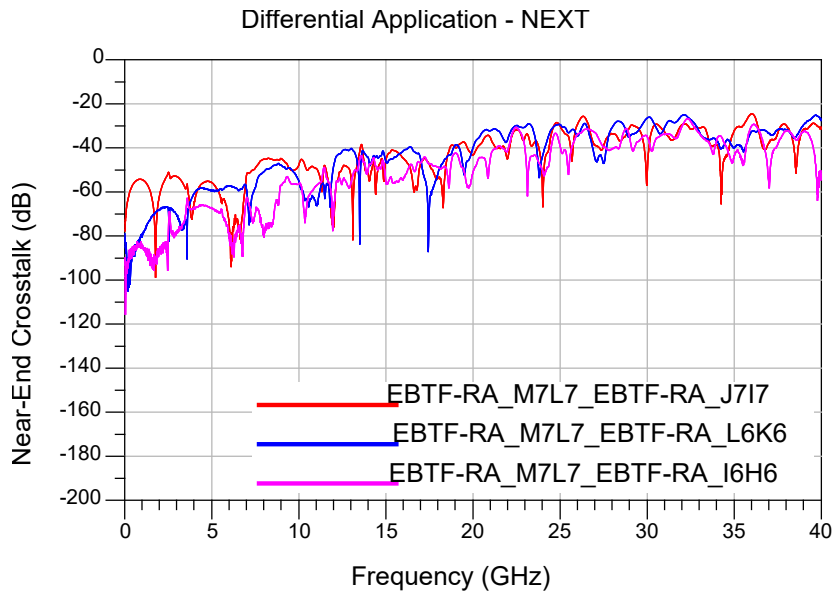


Figure 14

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

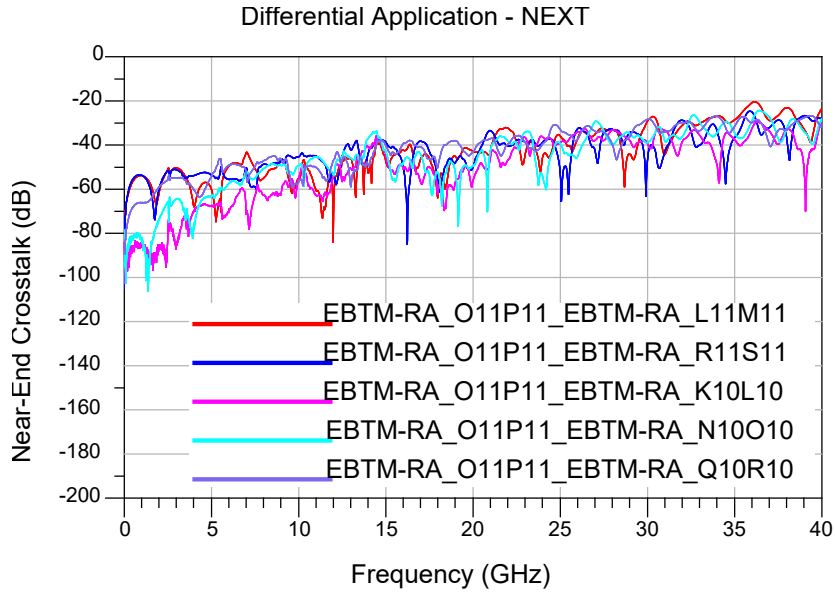


Figure 15

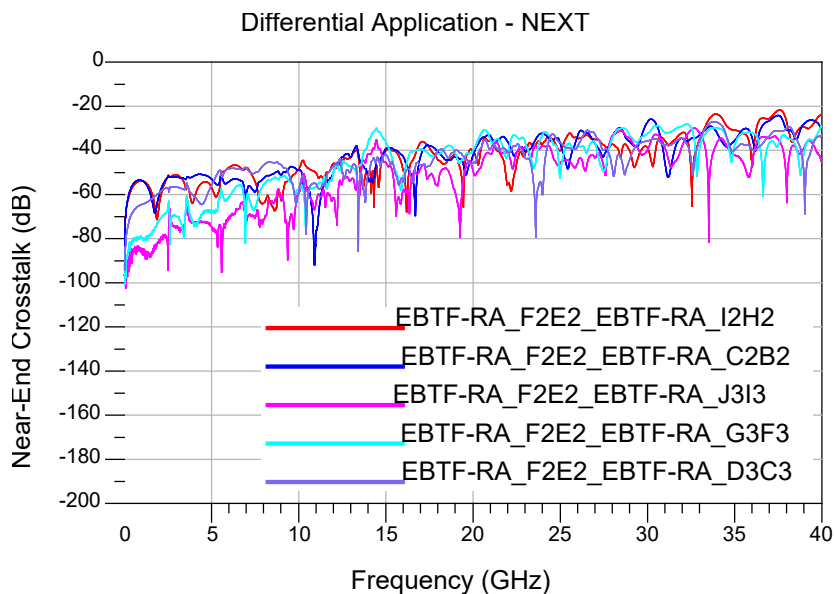


Figure 16

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

Differential Application – FEXT Configurations

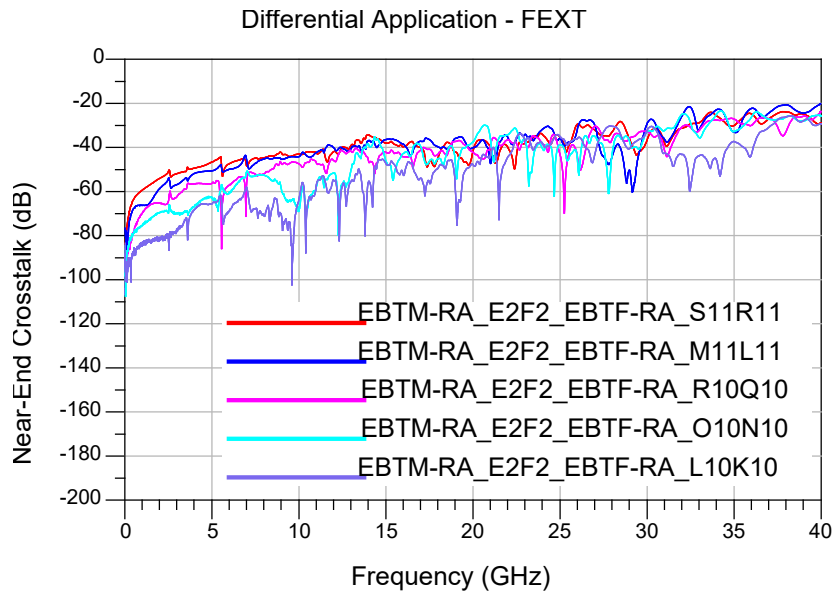


Figure 17

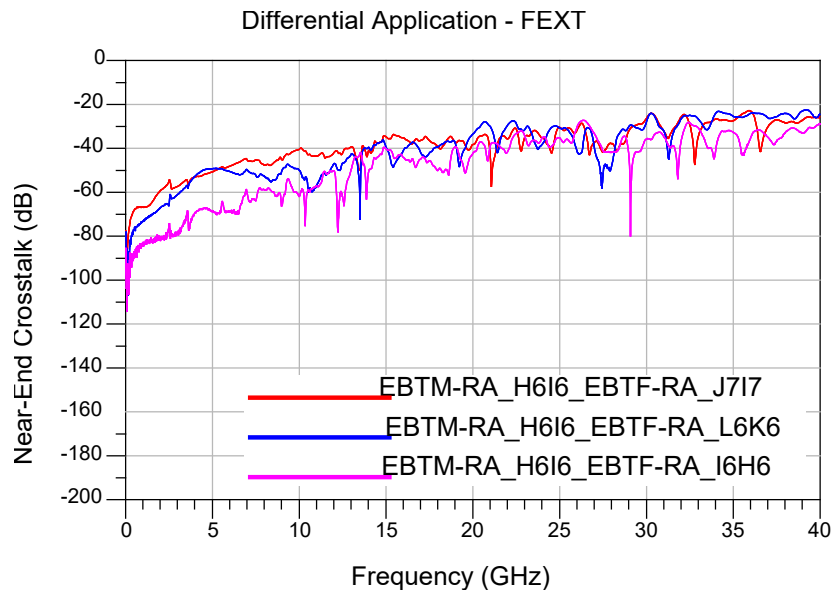


Figure 18

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

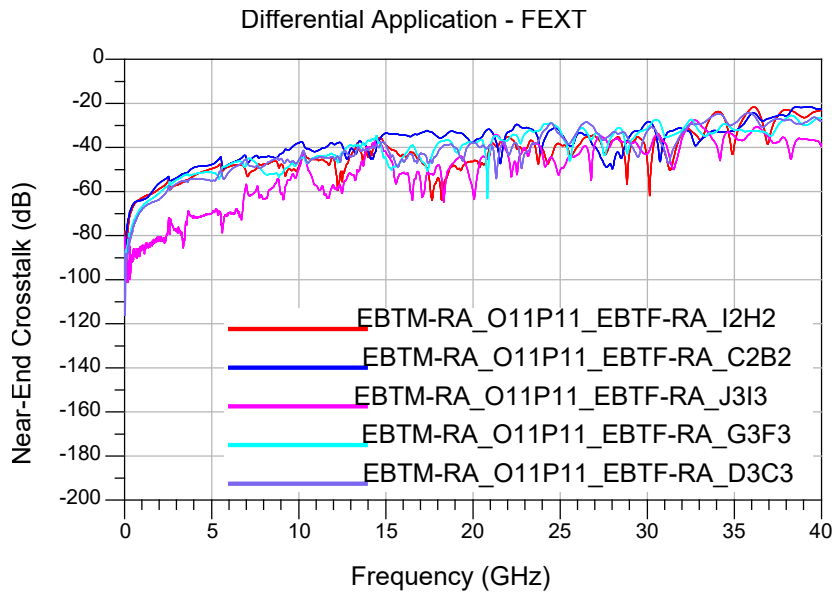


Figure 19

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

Appendix B – Time Domain Responses Differential Application – Impedance

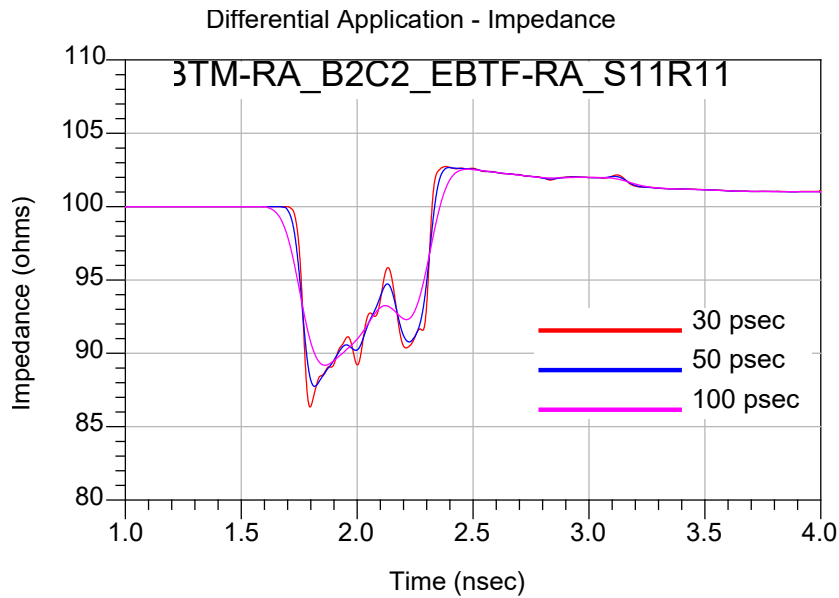


Figure 20

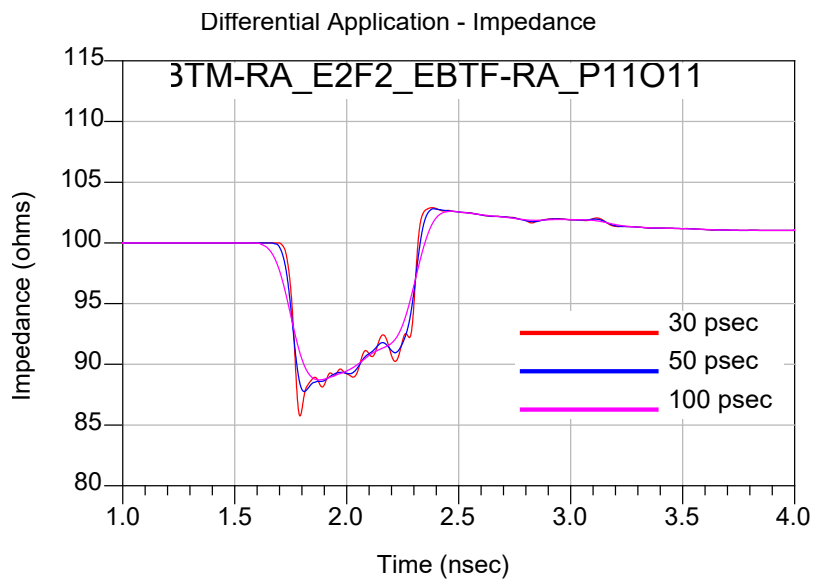


Figure 21

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

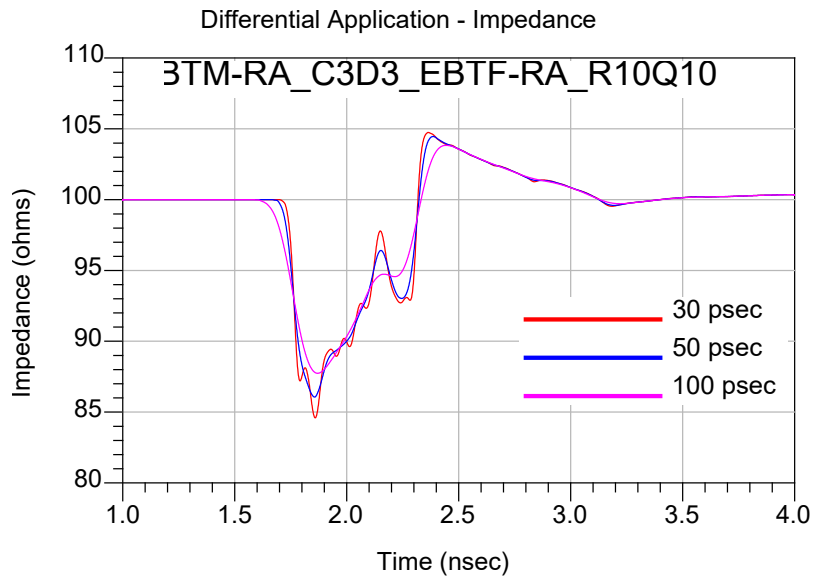


Figure 22

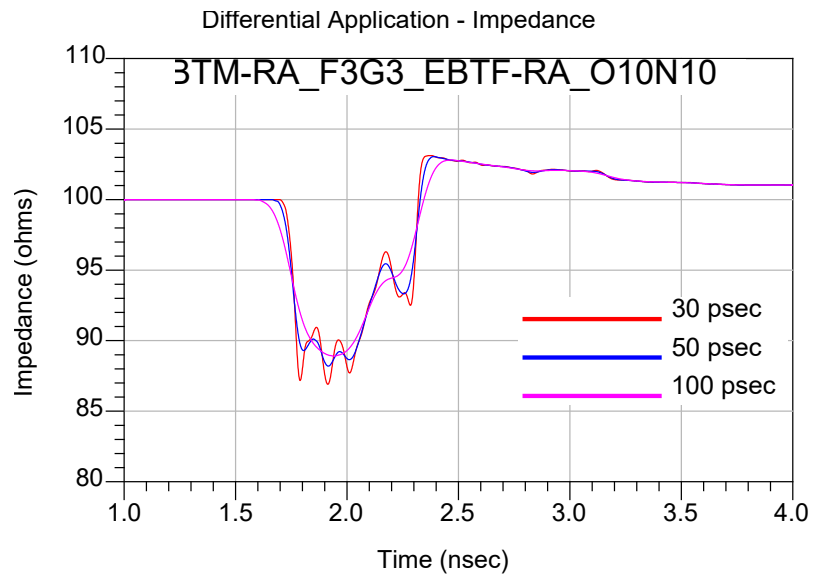


Figure 23

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

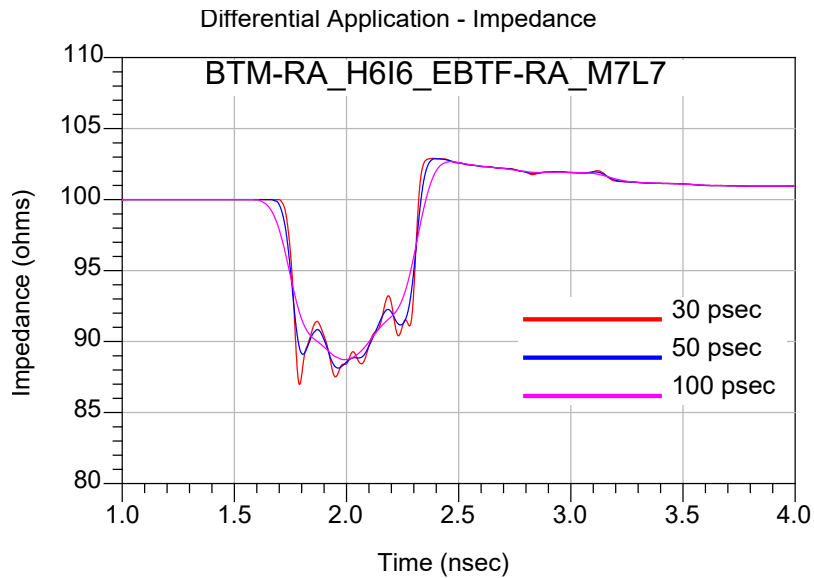


Figure 24

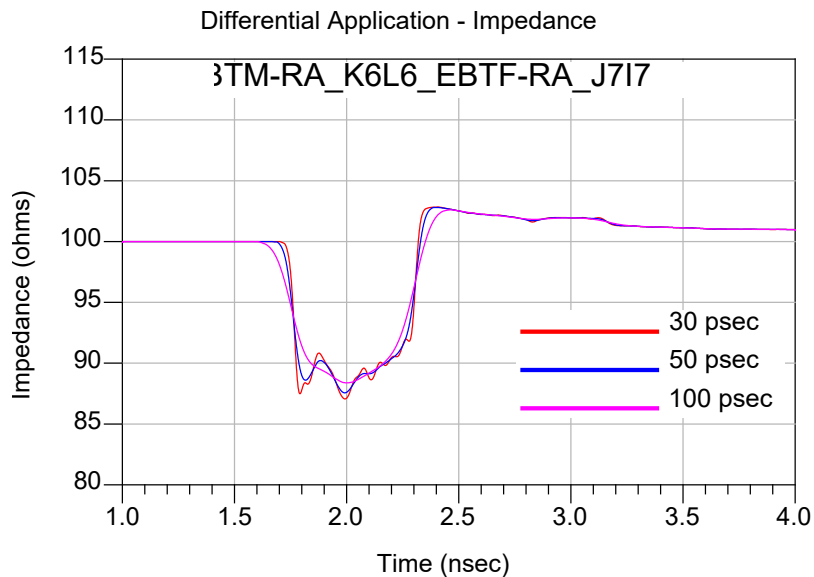


Figure 25

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

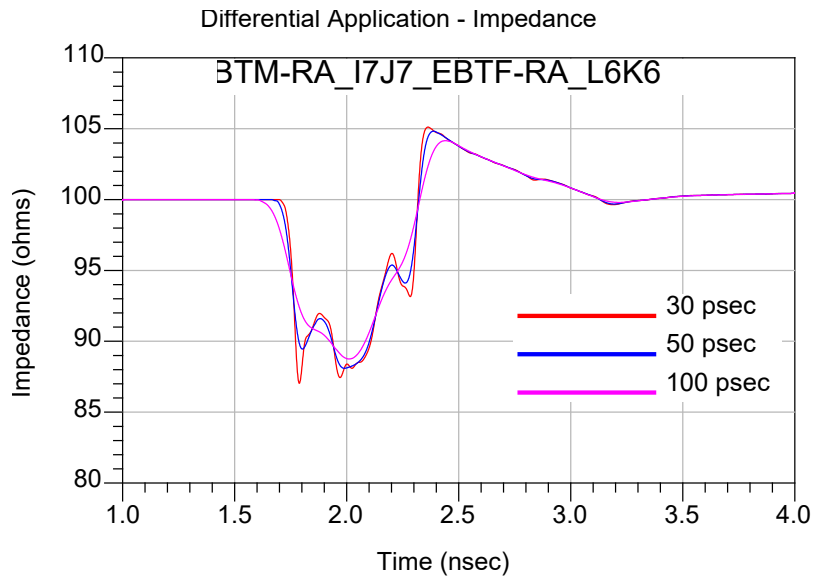


Figure 26

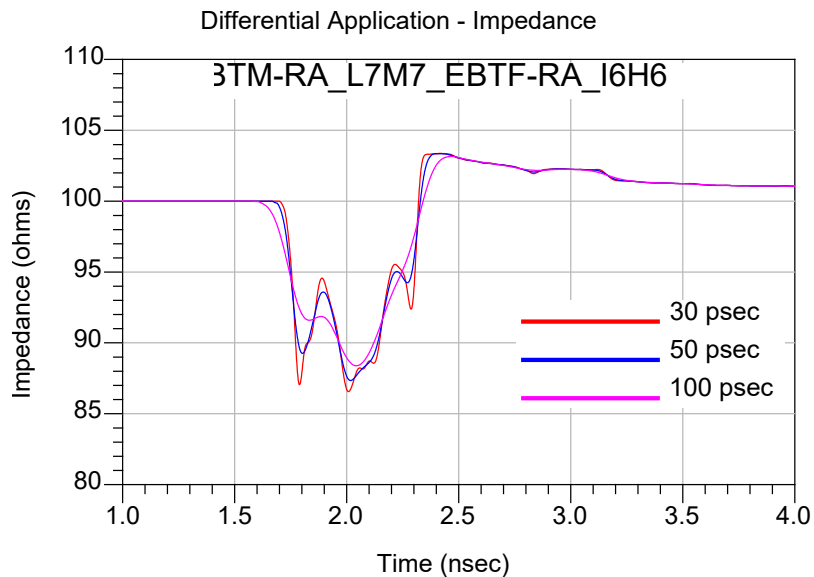


Figure 27

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

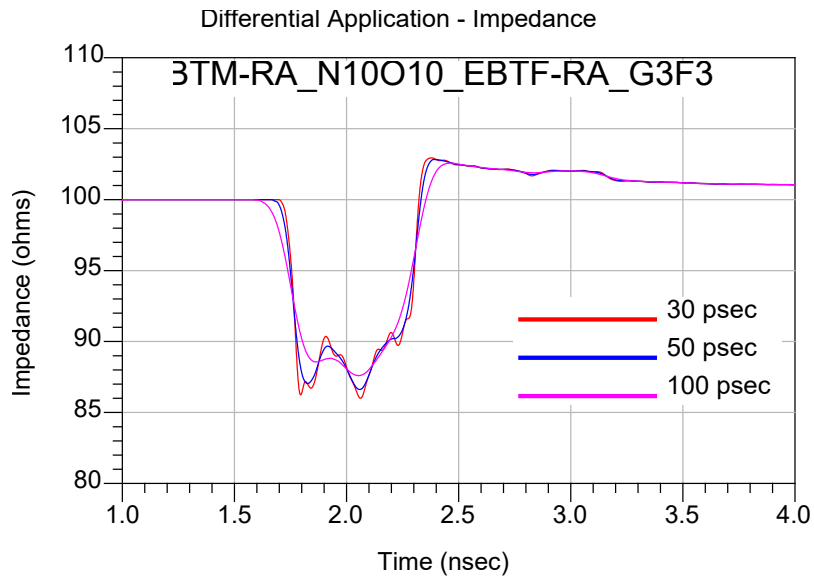


Figure 28

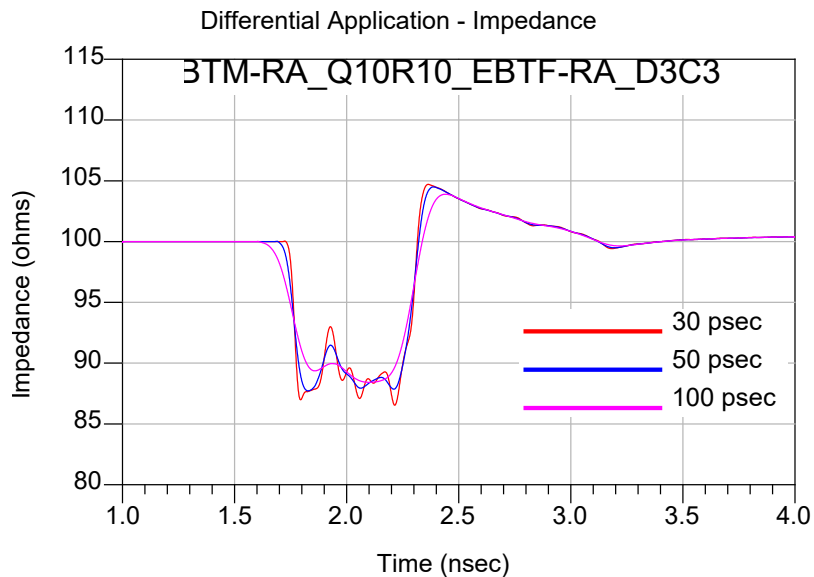


Figure 29

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

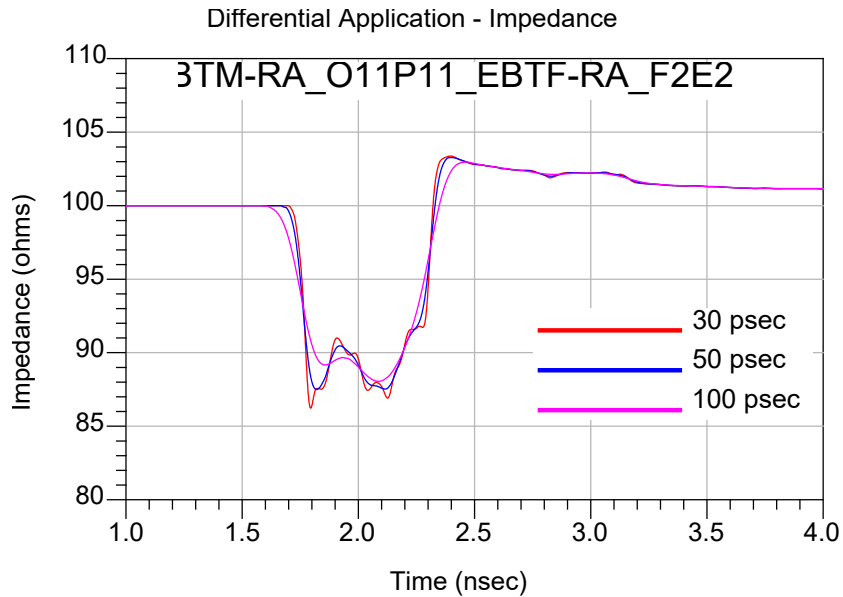


Figure 30

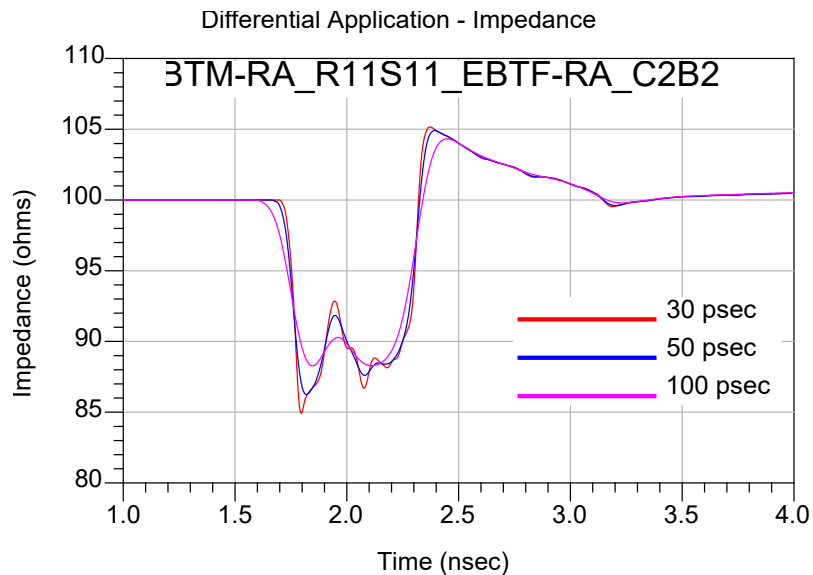


Figure 31

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

Differential Application – Propagation Delay

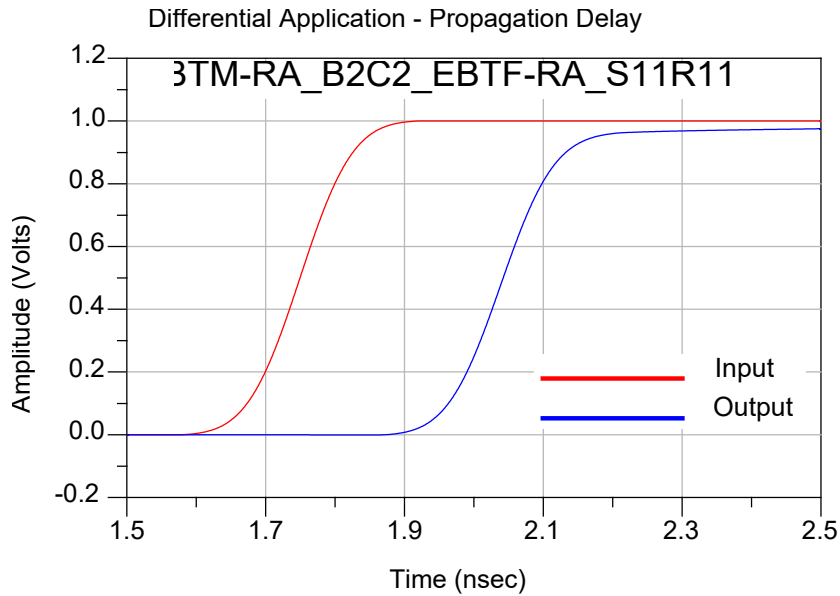


Figure 32

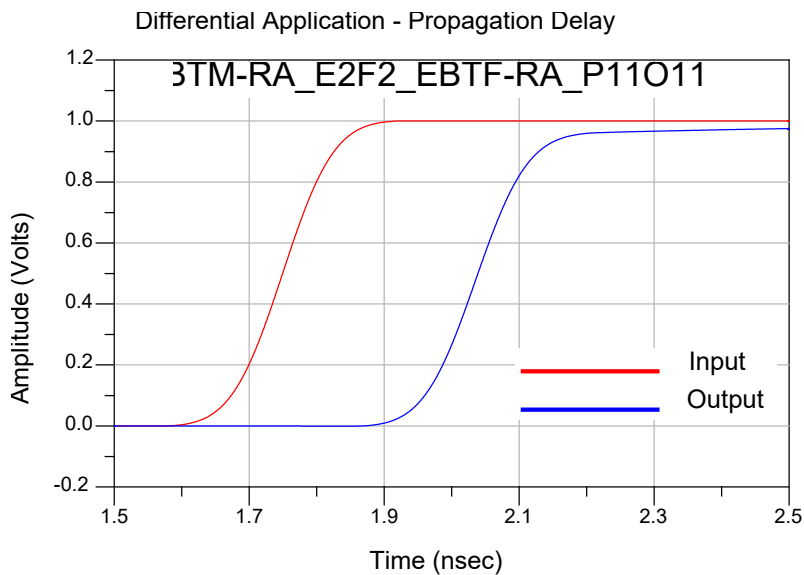


Figure 33

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

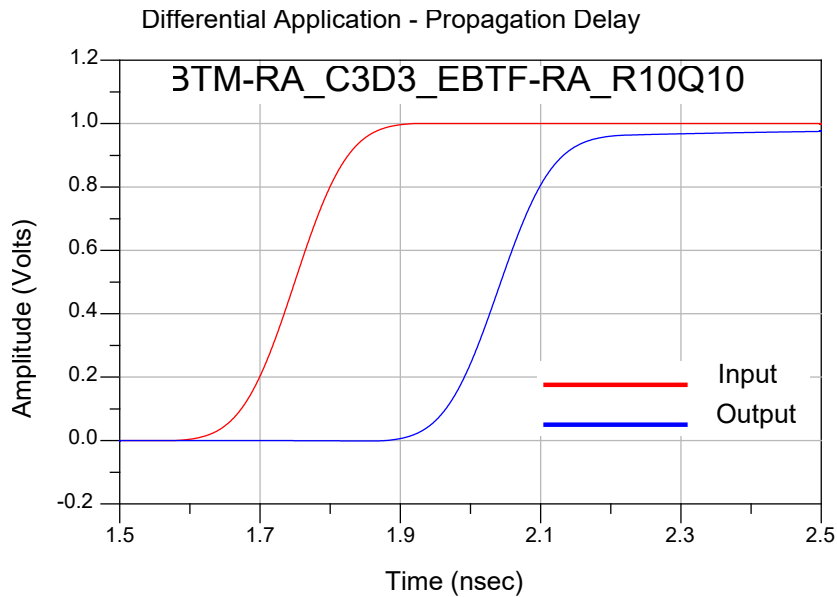


Figure 34

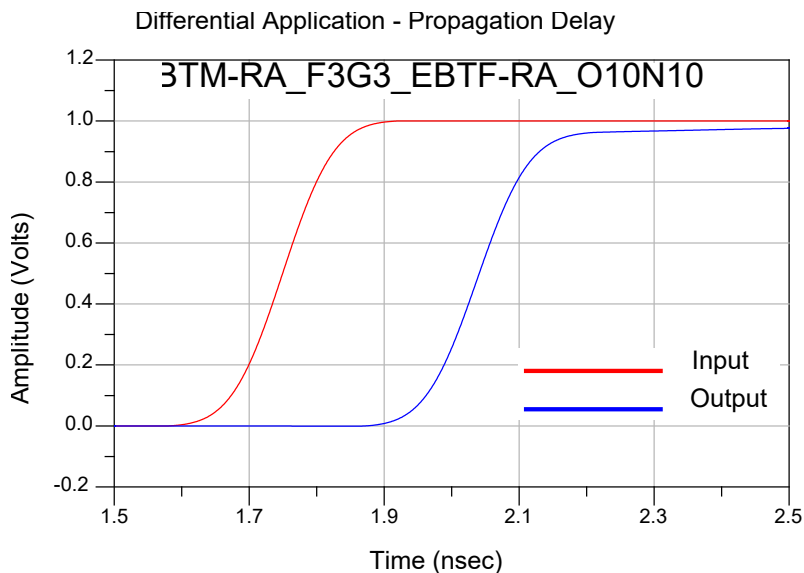


Figure 35

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

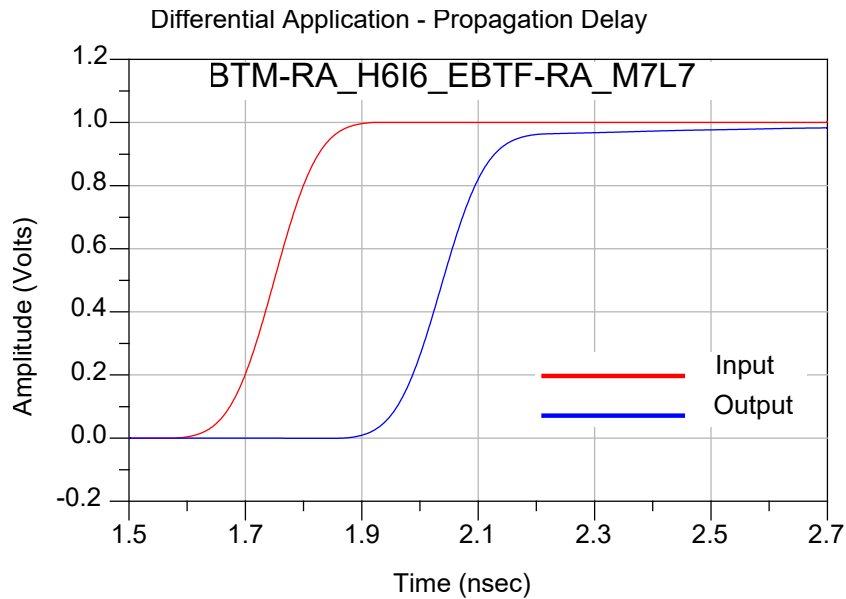


Figure 36

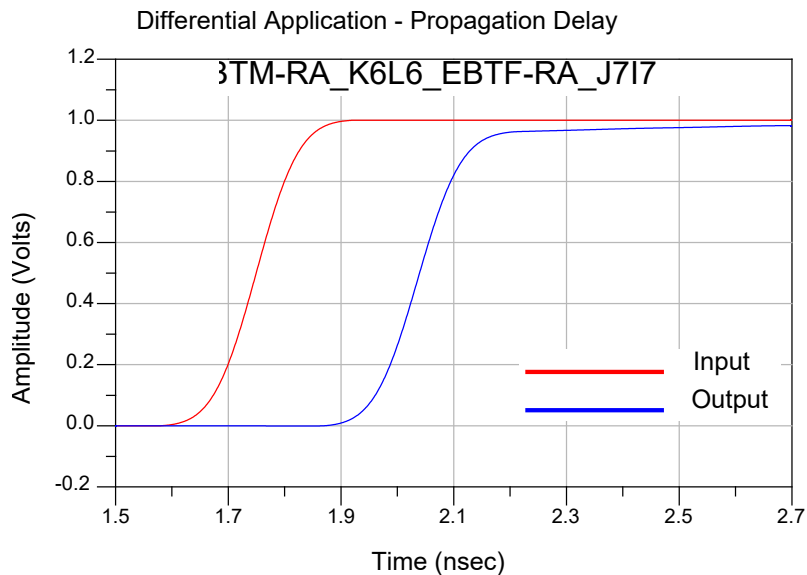


Figure 37

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

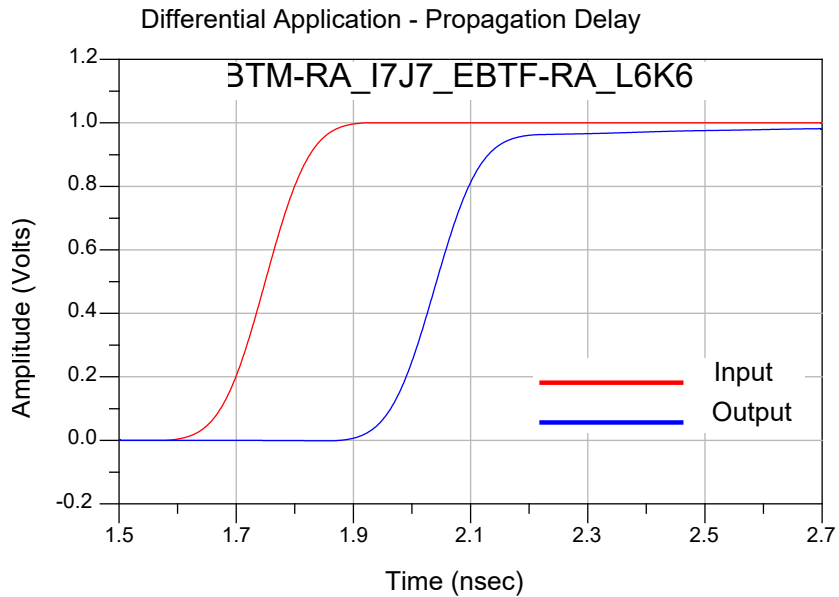


Figure 38

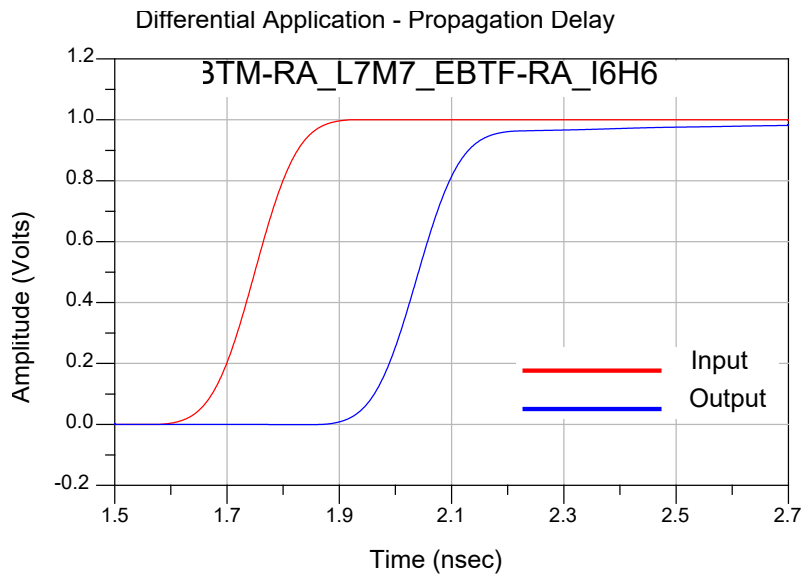


Figure 39

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

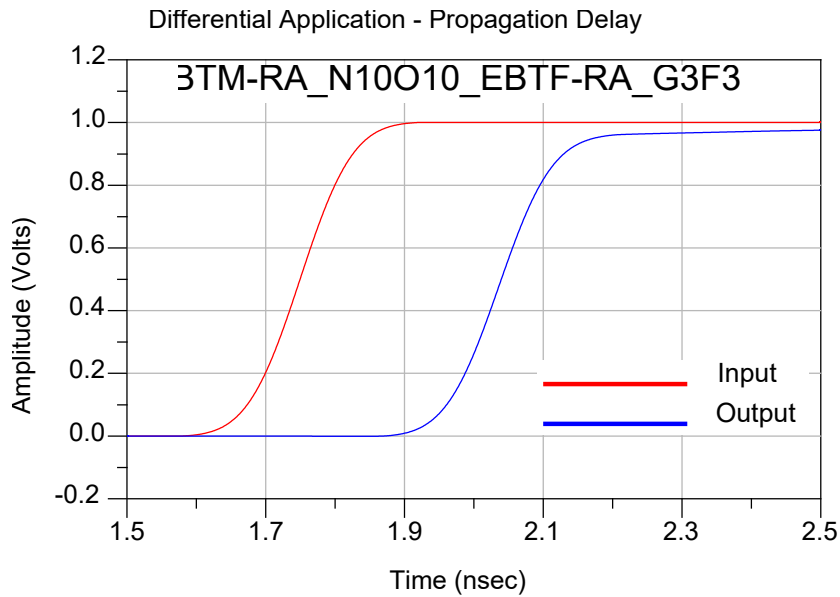


Figure 40

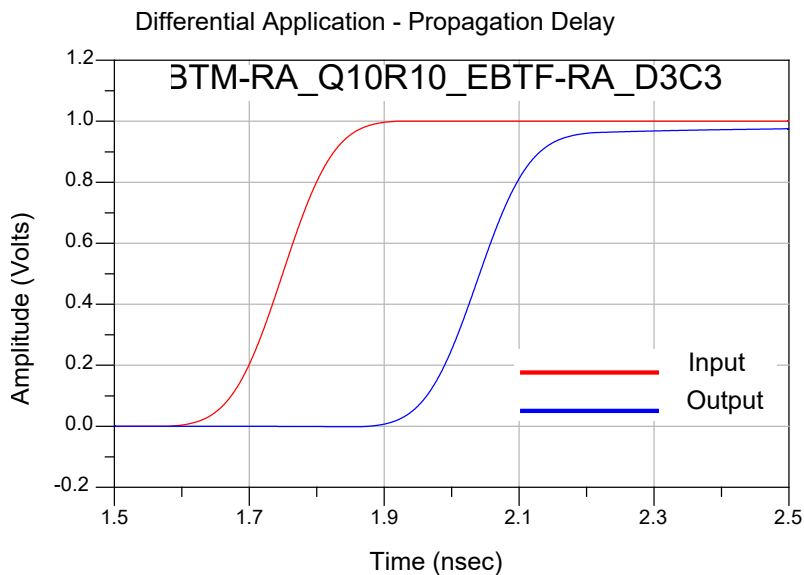


Figure 41

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

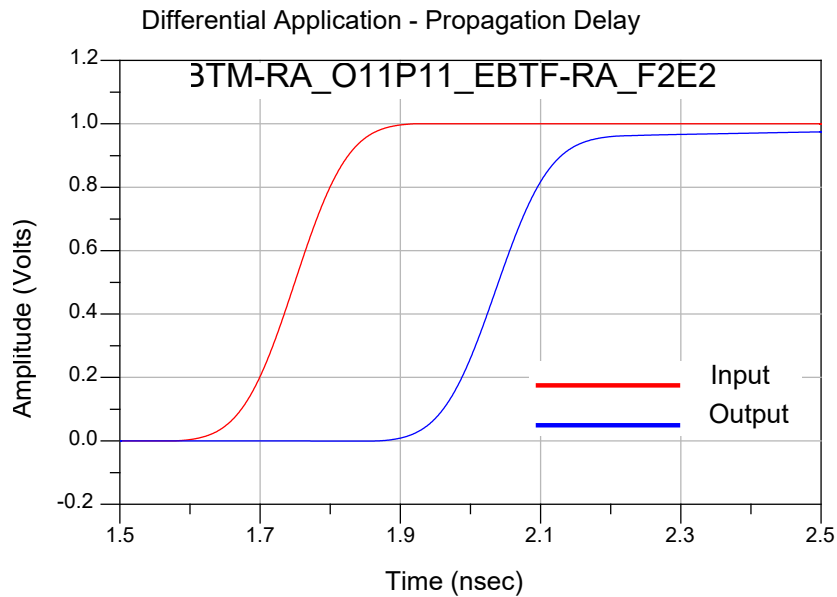


Figure 42

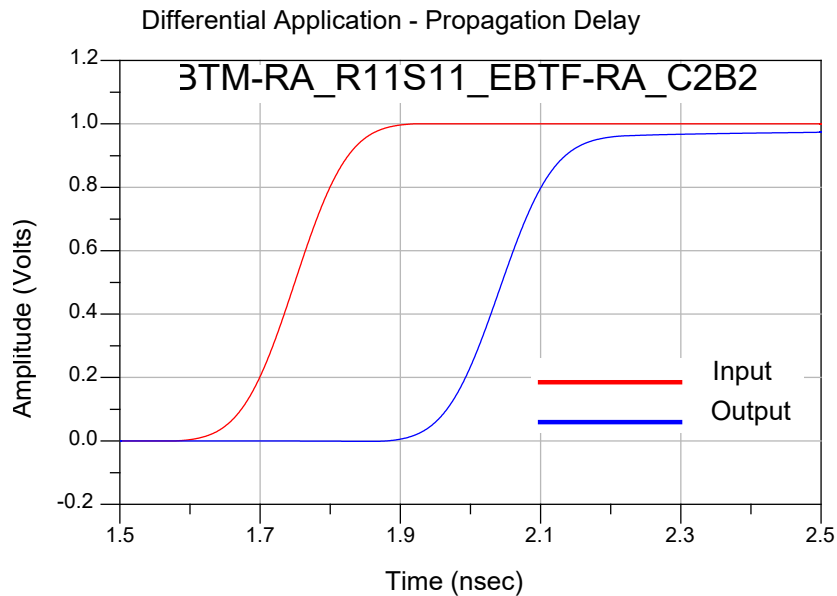


Figure 43

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

Appendix C – Product and Test System Descriptions

Product Description

Product test samples are EBTM-RA/EBTF-RA Series connectors. The part number is EBTM-6-12-2.0-S-RA-1 and EBTF-6-12-2.0-S-RA-1. A photo of the test samples mounted to SI test boards is shown below. The boards were populated with 2.4 mm connectors to reliable out to 50 GHz.

Test System Description

The test fixtures are composed of six-layer MT40 material with 50Ω signal trace and pad configurations designed for the electrical characterization of Samtec high speed connector products. A PCB mount 2.4mm connector is used to interface the PNA test cables to the test fixtures. Optimization of the 2.4mm launch was performed using full wave simulation tools to minimize reflections. The test fixtures and calibration kit are specific to the EBTx series connector set and identified by part number PCB-EBTMRS-110444-SIG-0; PCB-EBTMRM-110444-SIG-0; PCB-EBTMRL-110444-SIG-0; PCB-EBTFRS-110445-SIG-0; PCB-EBTFRM-110445-SIG-0 and PCB-EBTFRL-110445-SIG-0.

PCB-EBTMRX-110444-SIG-0 and PCB-EBTFRX-110445-SIG-0 Test Fixtures

Shown below is a photograph of the test board set.

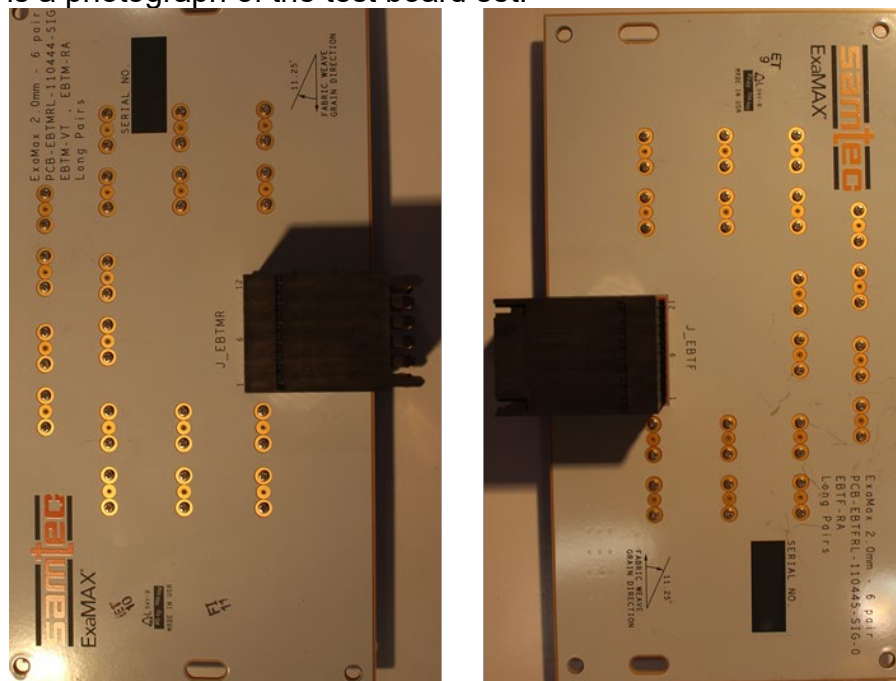


Figure 44

Series: EBTM-RA / EBTM-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

PCB Fixtures

The test fixtures used are as follows:

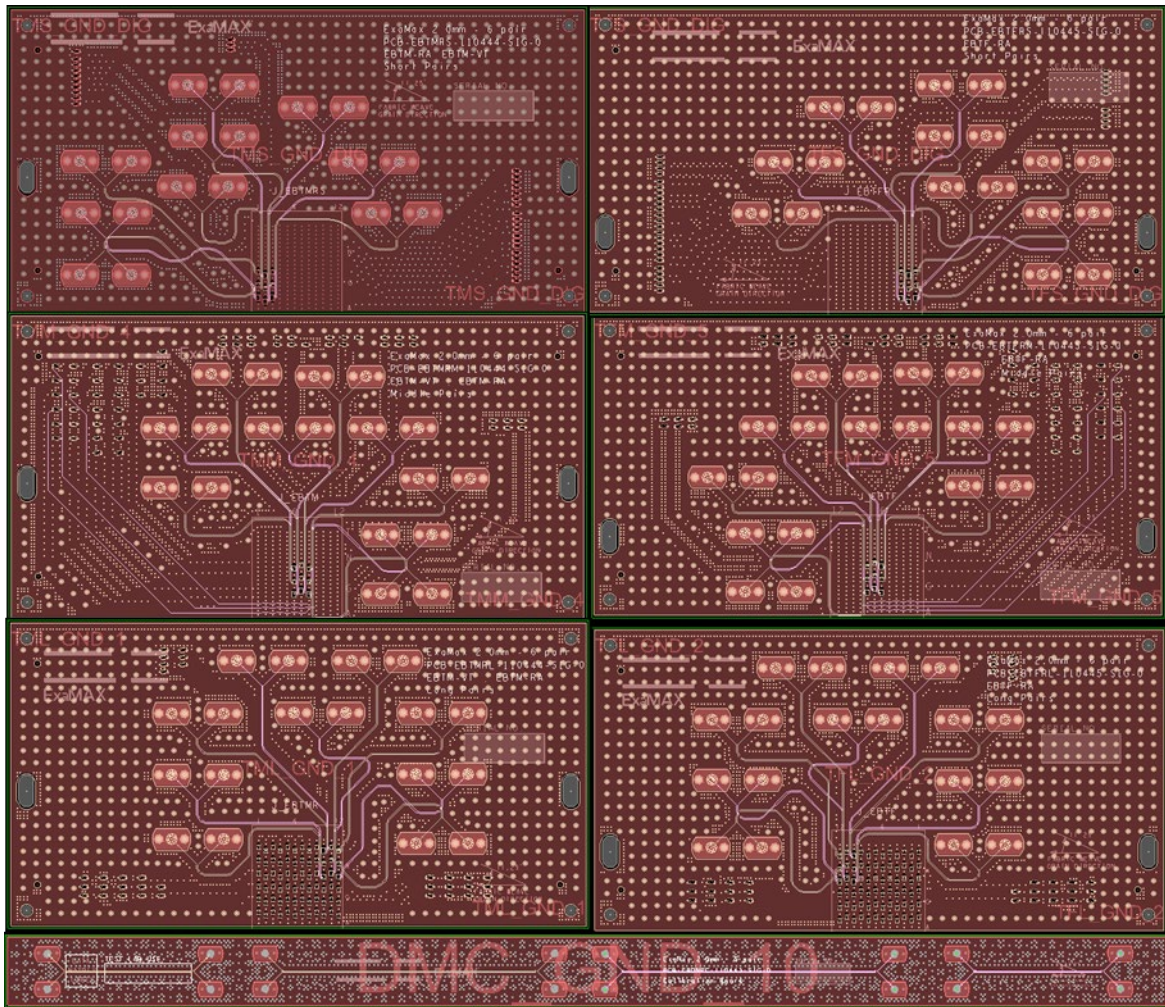


Figure 45

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

All traces on the test boards are length matched to 63.65 mm measured from the edge of the pad to the 2.4mm connector. The AFR calibration effectively removes 61.35 mm of test board trace effects. This means that 2.30 mm of test board trace length effects are included in both sides of test boards in the measurement. The S-Parameter measurement includes:

- A- The EBTM-RA/EBTF-RA Series connector set
- B- Test board vias, pads (footprint effects) for the EBTM-RA connector side.
- C- 2.30 mm of 0.142 mm wide microstrip trace.
- D- Test board vias, pads (footprint effects) for the EBTF-RA side.
- E- 2.30 mm of 0.142 mm wide microstrip trace.

The figure below shows the location of the measurement reference plane.

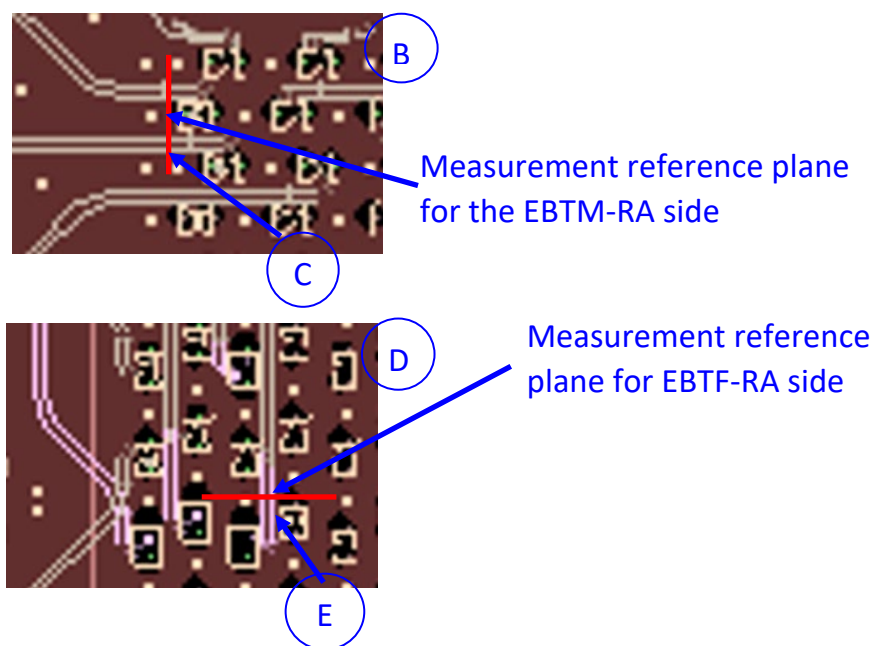


Figure 46

Series: EBTM-RA / EBTf-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

Appendix D – Test and Measurement Setup

For frequency domain measurements, the test instrument is the Keysight N5225B PNA-L network analyzer. Frequency domain data are obtained directly from the instrument and figures are generated by Keysight ADS. The network analyzer is configured as follows:

Start Frequency – 10 MHz

Stop Frequency – 40 GHz

Number of points – 4000

IFBW – 1 KHz

N5225B Measurement Setup

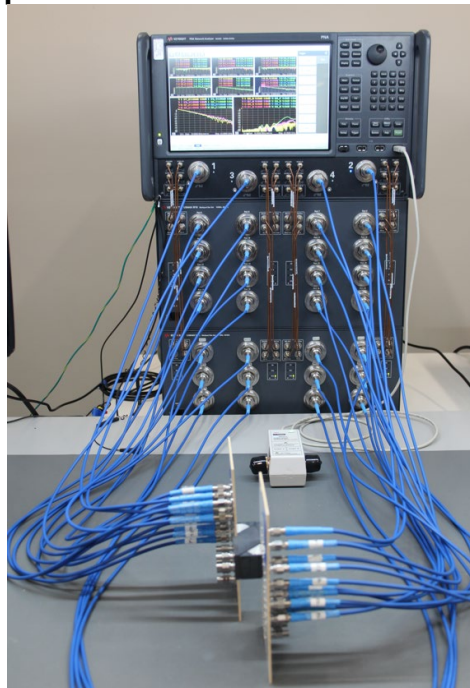


Figure 47

Test Instruments

<u>QTY</u>	<u>Description</u>
1	Keysight N5225B PNA Network Analyzer
1	Keysight N4694-60003 ECAL Module (10 MHz to 67 GHz)

Test Cables & Adapters

<u>QTY</u>	<u>Description</u>
32	1 m Junkosha 2.4mm male to female cables

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

Appendix E - Frequency and Time Domain Measurements

Frequency (S-Parameter) Domain Procedures

The quality of any data taken with a network analyzer is directly related to the quality of the calibration standards and the use of proper test procedures. For this reason, extreme care is taken in the design of the through calibration standards, the SI test boards, and the selection of the PCB vendor.

A coaxial SOLT calibration is performed using a N4694-60003 ECAL module. Then DUT measurements are performed under SOLT calibration. The measurements include the effect of test fixture. The measurements of the 2X THRU line standards are required to remove the test fixture effect.

Time Domain Procedures

Mathematically, Frequency Domain data can be transformed to obtain a Time Domain response. Perfect transformation requires Frequency Domain data from DC to infinity Hz. Fortunately, a very accurate Time Domain response can be obtained with bandwidth-limited data, such as measured with modern network analyzer.

The Time Domain responses were generated using Keysight ADS 2016. This tool has a transient convolution simulator, which can generate a Time Domain response directly from measured S-Parameters. An example of a similar methodology is provided in the Samtec Technical Note on domain transformation. http://www.samtec.com/Technical_Library/reference/articles/pdfs/tech-note_using-PLTS-for-time-domain-data_web.pdf

Propagation Delay (TDT)

The Propagation Delay is a measure of the Time Domain delay through the connector and footprint. A step pulse is applied to the touchstone model of the connector and the transmitted voltage is monitored. The same pulse is also applied to a reference channel with zero loss, and the Time Domain pulses are plotted on the same graph. The difference in time, measured at the 50% point of the step voltage is the propagation delay.

Near-End Crosstalk (TDT) & Far End Crosstalk (TDT)

A step pulse is applied to the touchstone model of the connector and the coupled voltage is monitored. The amplitude of the peak-coupled voltage is recorded and reported as a percentage of the input pulse.

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

Impedance (TDR)

Measurements involving digital pulses are performed using either Time Domain Reflectometer (TDR) or Time Domain Transmission (TDT) methods. The TDR method is used for the impedance measurements in this report.

The signal line(s) of the SUT's is energized with a TDR pulse and the far-end of the energized signal line is terminated in the test systems characteristic impedance (e.g., 50Ω or 100Ω terminations). By terminating the adjacent signal lines in the test systems characteristic impedance, the effects on the resultant impedance shape of the waveform are limited. The "best case" signal mapping was tested and is presented in this report.

Series: EBTM-RA / EBTF-RA

Description: ExaMAX® 2.00 mm High-Speed Backplane, 6 Pairs, Right-Angle Header mating to Right-Angle Receptacle, Alternate (Inverse) Mate (Pin 1 Up)

Appendix F – Glossary of Terms

ADS – Advanced Design Systems

FD – Frequency domain

FEXT – Far-End Crosstalk

GSG – Ground–Signal–Ground; geometric configuration

GSSG - Ground–Signal–Signal–Ground; geometric configuration

NEXT – Near-End Crosstalk

PCB – Printed Circuit Board

SE – Single-Ended

SI – Signal Integrity

SOLT – acronym used to define Short, Open, Load & Thru Calibration Standards

TD – Time Domain

TDA – Time Domain Analysis

TDR – Time Domain Reflectometry

TDT – Time Domain Transmission

Z – Impedance (expressed in ohms)